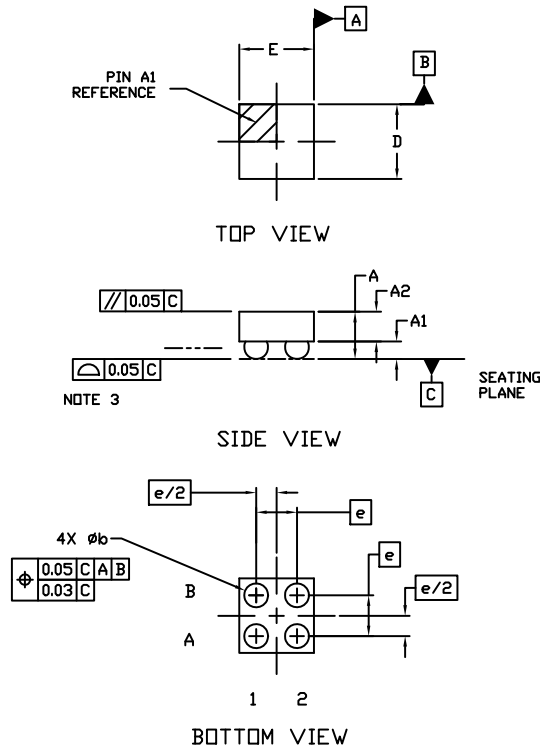**WLCSP4, 0.64x0.64x0.40**
CASE 567XW
ISSUE A

DATE 13 NOV 2019

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

2. CONTROLLING DIMENSION: MILLIMETERS

3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

4. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C..

TOP VIEW

SIDE VIEW

NOTE 3

BOTTOM VIEW

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.360	0.405	0.450
A1	0.130	0.150	0.170
A2	0.255 REF		
b	0.180	0.210	0.240
D	0.610	0.640	0.670
E	0.610	0.640	0.670
e	0.350 BSC		

**GENERIC
MARKING DIAGRAM***

XM

X = Specific Device Code
M = Month

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.
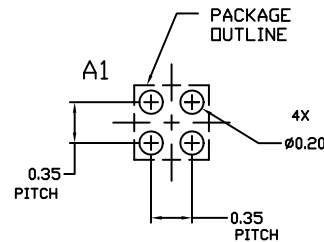
RECOMMENDED
MOUNTING FOOTPRINT

✳ For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON08375H		
DESCRIPTION:	WLCSP4, 0.64x0.64x0.40		**PAGE 1 OF 1**